LOTTE CHEMICAL

HOPELEX PCN-2001

Polycarbonate compound resin

General Information

Description

Easy mold release
Available in transparent, translucent and opaque color

Applications

Multi purpose grade (Electric & Electronic Housings, etc.)

Typical properties[1]

	Test method	Typical value	Unit
Physical			
Melt Flow Index, 300°C, 1.2 kg	ASTM D1238	-	g/10 min
Specific Gravity	ASTM D792	**1.2**	
Mold Shrinkage	ASTM D955	**0.5~0.7**	%
Mechanical			
Tensile Strength, yield, 50 mm/min	ASTM D638	**650**	kg_f/cm^2
Tensile Elongation, break, 50 mm/min	ASTM D638	**> 100**	%
Flexural Strength, yield, 10 mm/min	ASTM D790	**900**	kg_f/cm^2
Flexural Modulus, 10 mm/min	ASTM D790	**24,000**	kg_f/cm^2
IZOD Impact Strength, notched, 23°C, 1/8"	ASTM D256	**75**	kg_f·cm/cm
notched, 23°C, 1/4"	ASTM D256	-	kg_f·cm/cm
notched, -30°C, 1/8"	ASTM D256	-	kg_f·cm/cm
Thermal			
Heat Distortion Temp. 4.6 kg_f/cm^2	ASTM D648	-	°C
18.6 kg_f/cm^2	ASTM D648	**130**	°C
Vicat Softening Temp. Rate B/50	ASTM D1525	-	°C
Flammability			
UL94 V-2	UL94	**1.5**	mm
UL94 V-2	UL94	**3.0**	mm

Notes

ISO 9001, 14001, TS 16949

[1] Typical properties : these are not to be construed as specifications.

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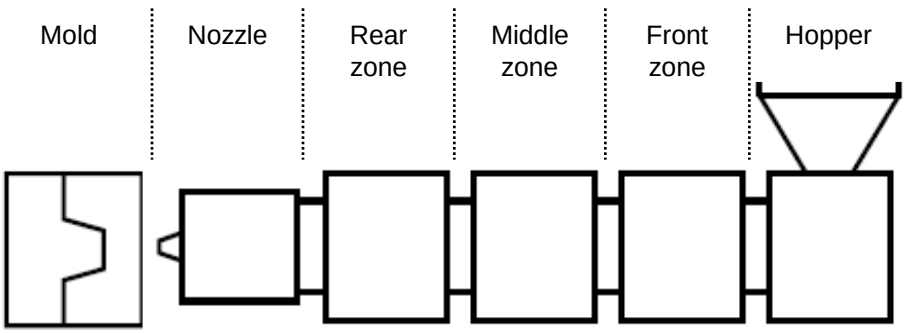
Processing guides[1]

		Typical value	Unit
Drying condition			
Drying temperature		**120**	°C
Drying time		**4**	hr
Maximum moisture content		**0.02**	%
Injection molding			
Melt temperature		**270 ~ 290**	°C
Nozzle temperature		**260 ~ 280**	°C
Barrel	**Rear zone**	**270 ~ 290**	°C
	Middle zone	**260 ~ 280**	°C
	Front zone	**250 ~ 270**	°C
Hopper temperature		**60 ~ 80**	°C
Mold temperature		**60 ~ 90**	°C



Recycling

Sprues and runners can be reground with virgin resin within the ratio of 20%. Care must be taken to ensure that the regrind is free from impurities and regrind should not be used in applications where impact performance and/or agency compliance are required.

Notes

ISO 9001, 14001, TS 16949

[1] Processing guides : Typical processing parameters are noted. Actual processing conditions will depend on machine size, mold design, material residence time, shot size, etc.